

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20220510003.0 Datasheet for SNx4HCT244, SN54HC688, SN74HC688, SNx4HCT240, SNx4HCT541, and CDx4HC573 Information Only

Date:May 11, 2022To:PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (<u>PCN ww admin team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE SN74HCT244N CUSTOMER PART NUMBER null

Technical details of this Product Change follow on the next page(s).

ation Number: 20220510003.0 Notification Date: May 11, 2022 Datasheet for SNx4HCT244, SN54HC688, SN74HC688, SNx4HCT240, SNx4HCT541 and CDx4HC573 Der Contact: PCN Manager Dept: Quality Services and CDx4HC573 Design Dept: Quality Services are Contact: PCN Manager Dept: Quality Services are Type:
Per Contact: PCN Manager Dept: Quality Services emply Site Design Wafer Bump Site eembly Site Data Sheet Wafer Bump Material eembly Process Data Sheet Wafer Bump Material eembly Materials Part number change Wafer Bump Process chanical Specification Test Site Wafer Fab Site chanical Specification Test Process Wafer Fab Materials wafer Fab Process Wafer Fab Process Wafer Fab Process Notification Details Wafer Fab Process Wafer Fab Process Notification Details Wafer Fab Process Step Process Notification Details Wafer Fab Process Step Process cluct datasheet(s) is being updated as summarized below. Step Process Process Step Process wing change history provides further details. Struments Step Process
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ction-to-ambient thermal resistance values increased. DW was 76.6 is now 109.1, DB was 89.4 is now
ction-to-ambient thermal resistance values increased. DW was 76.6 is now 109.1, DB was 89.4 is now
es from Revision E (February 2022) to Revision F (May 2022) Page ction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6, was 83 is now 131.8.
EXAS SN54HCT240, SN74HCT24 NSTRUMENTS SCLS174G – MARCH 1984 – REVISED MAY 20
es from Revision F (February 2022) to Revision G (May 2022) Pag
ction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6,
was 60 is now 113.4, PW was 83 is now 131.8
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es from Revision D (February 2022) to Revision E (May 2022) Page
ction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, DB was 70 is now 122.7
ction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, DB was 70 is now 122.7 as 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8
as 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8
EXAS CD54HC573, CD74HC57
EXAS SN54HCT541, SN INSTRUMENTS SCLS306E – JANUARY 1996 – REVIS es from Revision D (February 2022) to Revision E (May 2022)

The datasheet number will be changing.				
Device Family	Change From:	Change To:		
SNx4HCT244	SCLS175E	SCLS175F		
SN54HC688, SN74HC688	SCLS010E	SCLS010F		
SNx4HCT240	SCLS174F	SCLS174G		
SNx4HCT541	SCLS306D	SCLS306E		
CDx4HC573	SCLS454B	SCLS454C		

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/SN54HCT244

http://www.ti.com/product/SN54HC688

http://www.ti.com/product/SN54HCT240

http://www.ti.com/product/SN54HCT541

http://www.ti.com/product/CD54HC573

Error! Bookmark not defined.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

Product Affected.			
CD74HC573E	SN74HCT240DW	SN74HCT244DWRG4	SN74HCT541DWR
CD74HC573EE4	SN74HCT240DWG4	SN74HCT244N	SN74HCT541DWRE4
CD74HC573M	SN74HCT240DWR	SN74HCT244NE4	SN74HCT541DWRG4
CD74HC573M96	SN74HCT240DWRE4	SN74HCT244NS	SN74HCT541N
CD74HC573M96G4	SN74HCT240N	SN74HCT244NSR	SN74HCT541NE4
SN74HC688DW	SN74HCT240NS	SN74HCT244NSRG4	SN74HCT541NS
SN74HC688DWR	SN74HCT240NSR	SN74HCT244PW	SN74HCT541NSR
SN74HC688DWRE4	SN74HCT240PW	SN74HCT244PWE4	SN74HCT541NSRE4
SN74HC688DWRG4	SN74HCT240PWR	SN74HCT244PWG4	SN74HCT541NSRG4
SN74HC688N	SN74HCT240PWT	SN74HCT244PWR	SN74HCT541PW
SN74HC688NE4	SN74HCT244DBR	SN74HCT244PWRG4	SN74HCT541PWG4
SN74HC688PWR	SN74HCT244DW	SN74HCT244PWT	SN74HCT541PWR
SN74HC688PWRE4	SN74HCT244DWE4	SN74HCT541DBR	SN74HCT541PWRE4
SN74HC688PWRG4	SN74HCT244DWG4	SN74HCT541DW	SN74HCT541PWRG4
SN74HC688PWT	SN74HCT244DWR	SN74HCT541DWE4	SN74HCT541PWT
SN74HC688PWTG4	SN74HCT244DWRE4	SN74HCT541DWG4	

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN ww admin team@list.ti.com

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